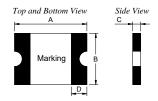


1, Physical Dimensions(size of 1206)

Unit:mm

Part Number	A		В		С		D	M1-:	
	Min	Max	Min	Max	Min	Max	Min	Marking	
KNSMD012/60	3.00	3.40	1.40	1.80	0.80	1.20	0.25	T01	



2. Electrical Characteristics

Part Number	I _H (A)	I _T (A)	V _{max} (V)	I max (A)	T _{trip} (Max time to trip) Current(A) Time(S)		Pd _{typ} (W)	$R_{min} (\Omega)$	$R1_{max}$ (Ω)
KNSMD012/60	0.12	0.29	60	10	1.00	0.20	0.40	1.350	8.500

I_H: Holding Current: maximum current at which the device will not trip in 25°C still air.

 I_T : Tripping Current minimum current at which the device will trip in 25°C still air.

V_{max}: Maximum voltage device can withstand without damage at rated current.

I max: Maximum fault current device can withstand without damage at rated voltage.

T trip: Maximum time to trip(s) at assigned current.

Pd_{typ}: Rated working power.

R min: Minimum resistance of device prior to trip at 25°C.

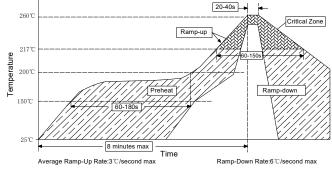
R1 max: Maximum resistance of device is measured one hours post reflow at 25°C.

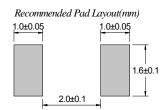
Noted: All electrical function test is conducted after PCB mounted.

3. Thermal Derating

KNSMD012/60	Maximum ambient operating temperature									
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C	
Hold Current(A)	0.19	0.17	0.15	0.12	0.11	0.1	0.09	0.08	0.07	
Trip Current(A)	0.46	0.41	0.36	0.29	0.27	0.24	0.22	0.19	0.17	

4. Solder Reflow Recommendations





Notes:If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

5. Package Information

Packing quantity:3500PCS/Reel

Note:Reel packaging per EIA-481-1 standard